

Agilent HyperTransport 3 Technologies Solution

Data Sheet



The HyperTransport analysis probes enable designers to debug, test, and verify compliance of 8 and 16 bit HyperTransport links. The analysis probe provides a mechanical, electrical and software interface between your 5.2 GT/s HyperTransport bus and an Agilent logic analyzer. The probe provides quick and reliable

connections to your system under test and has internal termination networks that minimize the effects of loading and reflections on your HyperTransport bus during probing. The protocol decode software decodes and displays incoming data on your logic analyzer to make it easy for you to debug your design problems.



Agilent Technologies

Features

- Analysis of HyperTransport bus up to 5.2 GT/s. Scalable high speed integrity architecture.
- Support configuration for 8 bit and 16 bit operation
- Full duplex mode (T_x and R_x) – DC coupled probe architecture with interposer probe for both single and dual lane measurement
- Non-intrusive probing of midbus using unique soft touch connectorless probing technology
- Logic analysis triggering and decoding of HyperTransport buses at the packet level with Packet Viewer software
- Triggering capability with raw 36-bit pattern matching and menu driven command triggering
- NOOP filtering with or without flow control

Complete system

Use a 16900 Series logic analyzer with the analysis probe in your development lab for design and functional validation of HyperTransport architectures. The analysis probe provides low-intrusion probing of the bus, packet analysis and packet triggering to help you pinpoint your problem areas quickly. The probe supports data scrambling and flexible lane widths so you can make sure your design is consistent with HyperTransport standards. The interposer and midbus probing option make it easy for you to reliably connect to your device.



Figure 1. Ensure non-intrusive connection to an embedded system with a midbus probe using soft touch connectorless probing technology.

HT3 Midbus Pin	HT3 Signal	HT3 Midbus Pin	HT3 Signal
—	* No Pad *	G1	GND
2	GND	1	NC
4	NC	3	NC
6	NC	5	GND
8	GND	7	CAD[0]_H
10	CAD[1]_H	9	CAD[0]_L
12	CAD[1]_L	11	GND
14	GND	13	CAD[2]_H
16	CAD[3]_H	15	CAD[2]_L
18	CAD[3]_L	17	GND
20	GND	19	PWROK_H
22	NC	21	PWROK_L
24	NC	23	GND
26	GND	25	CLK[0]_H
28	CAD[4]_H	27	CLK[0]_L
30	CAD[4]_L	29	GND
32	GND	31	CAD[5]_H
34	CAD[6]_H	33	CAD[5]_L
36	CAD[6]_L	35	GND
38	GND	37	CAD[7]_H
40	CTL[0]_H	39	CAD[7]_L
42	CTL[0]_L	41	GND
44	GND	43	RESET_H
46	LDT_STOP_H	45	RESET_L
48	LDT_STOP_L	47	GND
G2	GND	—	* No Pad *

Table 1. Pinout for CAD[7:0] (Lower)

HT3 Midbus Pin	HT3 Signal	HT3 Midbus Pin	HT3 Signal
—	* No Pad *	G1	GND
2	GND	1	NC
4	NC	3	NC
6	NC	5	GND
8	GND	7	CAD[8]_H
10	CAD[9]_H	9	CAD[8]_L
12	CAD[9]_L	11	GND
14	GND	13	CAD[10]_H
16	CAD[11]_H	15	CAD[10]_L
18	CAD[11]_L	17	GND
20	GND	19	PWROK_H
22	NC	21	PWROK_L
24	NC	23	GND
26	GND	25	CLK[1]_H
28	CAD[12]_H	27	CLK[1]_L
30	CAD[12]_L	29	GND
32	GND	31	CAD[13]_H
34	CAD[14]_H	33	CAD[13]_L
36	CAD[14]_L	35	GND
38	GND	37	CAD[15]_H
40	CTL[1]_H	39	CAD[15]_L
42	CTL[1]_L	41	GND
44	GND	43	RESET_H
46	LDT_STOP_H	45	RESET_L
48	LDT_STOP_L	47	GND
G2	GND	—	* No Pad *

Table 2. Pinout for CAD[15:8] (Upper)

Probe connections

Soft Touch Twin Footprint

Figure 3 below shows Agilent Technologies Soft Touch Twin footprint with today's HT1 tools utilizing the Industry Standard Connectorless Probe and with Agilent's HT3 tools of the future. If you want to design a midbus footprint into your system that will accommodate both today's HT1 tools and Agilent's HT3 tool, you should design in the "Soft Touch Twin" footprint.

There is one minor change to the Industry Standard Connectorless Probe footprint: pin A27 must be tied to GND in the Soft Touch Twin pinout, rather than to ID[0] as in the original Industry Standard pinout. In addition to this change, the other pinout requirement to make special note of is that the PWROK pair is routed to pins C12 and C13 in addition to pins B26 and B27 in the Industry Standard footprint. Finally, please note that positions C1 and C27 have no pads in the Soft Touch Twin footprint. A red font is used for these pads numbers and signal names in the tables below to highlight their unique handling in the Soft Touch Twin pinout for HT3. Note also that the differential signals in rows B and C are essentially "double probed."

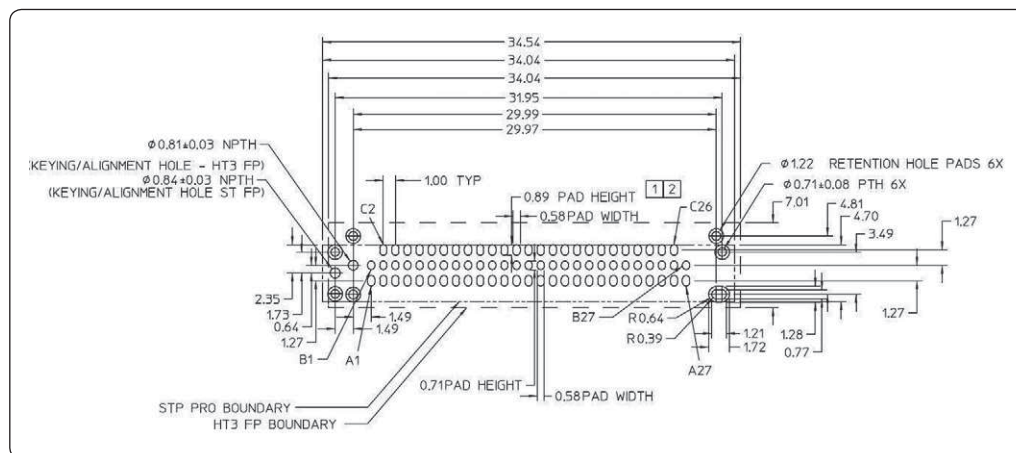


Figure 3. "Soft Touch Twin" footprint for HT1 and HT3 tool

Soft Touch Twin Pin	HT3 Signal	Soft Touch Twin Pin	HT3 Signal	Soft Touch Twin Pin	HT3 Signal
A1	NC	B1	ID[2]	C1	* No Pad *
A2	NC	B2	NC	C2	GND
A3	GND	B3	NC	C3	NC
A4	NC	B4	GND	C4	NC
A5	NC	B5	CAD[0]_H	C5	GND
A6	GND	B6	CAD[0]_L	C6	CAD[0]_H
A7	CAD[1]_H	B7	GND	C7	CAD[0]_L
A8	CAD[1]_L	B8	CAD[2]_H	C8	GND
A9	GND	B9	CAD[2]_L	C9	CAD[2]_H
A10	CAD[3]_H	B10	GND	C10	CAD[2]_L
A11	CAD[3]_L	B11	NC	C11	GND
A12	GND	B12	NC	C12	PWROK_H
A13	NC	B13	GND	C13	PWROK_L
A14	NC	B14	CLK[0]_H	C14	GND
A15	GND	B15	CLK[0]_L	C15	CLK[0]_H
A16	CAD[4]_H	B16	GND	C16	CLK[0]_L
A17	CAD[4]_L	B17	CAD[5]_H	C17	GND
A18	GND	B18	CAD[5]_L	C18	CAD[5]_H
A19	CAD[6]_H	B19	GND	C19	CAD[5]_L
A20	CAD[6]_L	B20	CAD[7]_H	C20	GND
A21	GND	B21	CAD[7]_L	C21	CAD[7]_H
A22	CTL[0]_H	B22	GND	C22	CAD[7]_L
A23	CTL[0]_L	B23	RESET_H	C23	GND
A24	GND	B24	RESET_L	C24	RESET_H
A25	LDT_STOP_H	B25	ID[1]	C25	RESET_L
A26	LDT_STOP_L	B26	PWROK_H	C26	GND
A27	GND	B27	PWROK_L	C27	* No Pad *

Table 3. Soft Touch Twin pinout for CAD[7:0] (Lower)

Soft Touch Twin Pin	HT3 Signal	Soft Touch Twin Pin	HT3 Signal	Soft Touch Twin Pin	HT3 Signal
A1	NC	B1	ID[2]	C1	* No Pad *
A2	NC	B2	NC	C2	GND
A3	GND	B3	NC	C3	NC
A4	NC	B4	GND	C4	NC
A5	NC	B5	CAD[8]_H	C5	GND
A6	GND	B6	CAD[8]_L	C6	CAD[8]_H
A7	CAD[9]_H	B7	GND	C7	CAD[8]_L
A8	CAD[9]_L	B8	CAD[10]_H	C8	GND
A9	GND	B9	CAD[10]_L	C9	CAD[10]_H
A10	CAD[11]_H	B10	GND	C10	CAD[10]_L
A11	CAD[11]_L	B11	NC	C11	GND
A12	GND	B12	NC	C12	PWROK_H
A13	NC	B13	GND	C13	PWROK_L
A14	NC	B14	CLK[1]_H	C14	GND
A15	GND	B15	CLK[1]_L	C15	CLK[1]_H
A16	CAD[12]_H	B16	GND	C16	CLK[1]_L
A17	CAD[12]_L	B17	CAD[13]_H	C17	GND
A18	GND	B18	CAD[13]_L	C18	CAD[13]_H
A19	CAD[14]_H	B19	GND	C19	CAD[13]_L
A20	CAD[14]_L	B20	CAD[15]_H	C20	GND
A21	GND	B21	CAD[15]_L	C21	CAD[15]_H
A22	CTL[1]_H	B22	GND	C22	CAD[15]_L
A23	CTL[1]_L	B23	RESET_H	C23	GND
A24	GND	B24	RESET_L	C24	RESET_H
A25	LDT_STOP_H	B25	ID[1]	C25	RESET_L
A26	LDT_STOP_L	B26	PWROK_H	C26	GND
A27	GND	B27	PWROK_L	C27	* No Pad *

Table 4. Soft Touch Twin pinout for CAD[15:8] (Upper)

Interposer probe

The high-speed signals along with DC level startup conditions have made it almost impossible to use typical AC coupled probe architectures (snooping probe) without significantly effecting the measurement. The Interposer probe is a DC coupled probe that acts as a “man-in-the-middle” between the CPU and the downstream device and sends a buffered copy of the link data to the HT3 logic analysis probe for analysis. The end result is full eyes at probe and target since the signals are buffered and sent back out to the target and the probe.



Figure 4. DC coupled interposer probe sends buffered copy of the link data from the target to the HT3 logic analysis probe.

The Interposer probe has configurations for both single lane (L1) and dual lane (L1L0) applications. The dual lane socket can be used in single lane mode (L1 or L0) if desired. The Interposer solution along with LAI can be ordered from Astek Corporation as a single unit. The table below gives the configurations allowed with the current HT3 LAI and Interposer probe system for various applications.

	Number of LAIs required	Number of single lane Interposers required	Number of Dual Lane Interposers required (use one or two lanes)
x8 US/DS*	1	1	1
x16 US or DS**	1	1	1
x16 US/DS	2	1	1
2 lanes x16 US/DS	4	N/A	1***

* US/DS corresponds to full-duplex upstream and downstream.
 ** US or DS corresponds to either upstream or downstream.
 *** Dual lane measurements require some additional hardware over single lane.

HyperTransport 3 analysis probe

The HyperTransport analysis probe is capable of probing at a serial data rate of 5.2 Gb/s – it's the speed of standard HyperTransport 3 bus so you can be confident your bus works at HyperTransport 3 speeds. The probe monitors two directions of x8 and x16 links so you can accurately capture the packet of interest. The probe is designed to handle a single, unidirectional link or a bidirectional link.

Protocol decode software

The analysis probe, which includes protocol decode software for 16900 Series logic analyzers, acquires serial data, converts it to parallel form, recognizes and filters packets, and clocks the information into the analyzer. Data sent to the logic analyzer includes:

- Captured data
- Packet type and state information
- Packet recognizers and error indicators

This data is processed by the protocol decoder for display of packets, transactions and errors. You can view the packet decode data with the Packet Viewer tool. Although the probe hardware has the ability to filter and trigger, the software interface provides bits arranged to support the use of logic-analyzer-based trigger functions, even on packet-based data. The decoder detects packet types and checks packet delimiters (minimal protocol checking).

Packet Viewer software

Packet Viewer software is a powerful tool for easy analysis of protocol traffic. Packet viewer provides bidirectional information in a single display. Packet viewer allows packet-to-packet comparisons and detailed information on each lane, header format and payload.

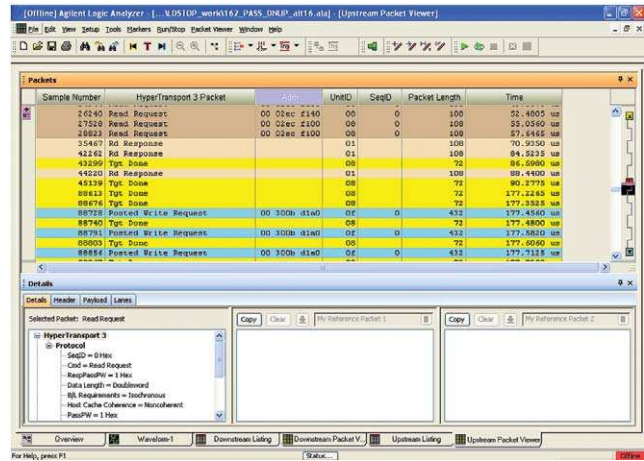


Figure 5. Packet Viewer – see packet and lane decode in an intuitive format.

Configuration guide

Bidirectional x8 lane width or one directional x16 lane width – Midbus probe

Product	Description	Quantity
AHT3-LAI-01	HyperTransport 3 analysis probe	1
One of the following 16900 Series logic analyzers:		
16902B	6-slot mainframe with 15-in touch display	1
One of the following modules:		
16950B	68-channel 4 GHz timing, 667 MHz state logic analysis module	3
16951B	68-channel 4 GHz timing, 667 MHz state/deep logic analysis module	3
N4246A	Midbus probe bi-directional X8 for HT3 5.2GB/s	2
E5378A	34-ch single-ended SAMTEC connector probe, connects to 90-pin LA cable	5

Bidirectional x8 lane width or one bidirectional x16 lane width – Interposer probe

Product	Description	Quantity
AHT3-LAI-01	HyperTransport 3 analysis probe	1
16902B	6-slot mainframe with 15-in touch display	1
One of the following modules:		
16950B	68-channel 4 GHz timing, 667 MHz state logic analysis module	3
16951B	68-channel 4 GHz timing, 667 MHz state/deep logic analysis module	3
One of the following interposer:		
Single lane AHT3-INT-01	RHL1 Single Lane Interposer	1
Dual lane AHT3-INT-02	L1L0 Dual Lane Interposer	1
Dual lane AHT3-ADP-01	Dual lane additional adapter kit (Only needed for Dual Lane measurements using the L0L1 Dual Lane Interposer, AHT3-INT-02)	1
E5378A	34-ch single-ended SAMTEC connector probe, connects to 90-pin LA cable	6

Ordering information

Model number	Product
AHT3-LAI-01	HyperTransport 3 Analysis Probe
AHT3-INT-01	RHL1 Single Lane Interposer
AHT3-INT-02	L1L0 Dual Lane Interposer
AHT3-ADP-01	Dual Lane additional adapter kit
	Contact information: 5055 Corporate Plaza Drive, Colorado Springs, CO 80919 Phone: 1-(866)-427-8351 Fax: 1-(719)-260-1668 Company URL: www.astekcorp.com



Agilent Email Updates

www.agilent.com/find/emailupdates
Get the latest information on the products and applications you select.



Agilent Direct

www.agilent.com/find/agilentdirect
Quickly choose and use your test equipment solutions with confidence.



www.agilent.com/find/open
Agilent Open simplifies the process of connecting and programming test systems to help engineers design, validate and manufacture electronic products. Agilent offers open connectivity for a broad range of system-ready instruments, open industry software, PC-standard I/O and global support, which are combined to more easily integrate test system development.



www.lxistandard.org
LXI is the LAN-based successor to GPIB, providing faster, more efficient connectivity. Agilent is a founding member of the LXI consortium.

Remove all doubt

Our repair and calibration services will get your equipment back to you, performing like new, when promised. You will get full value out of your Agilent equipment throughout its lifetime. Your equipment will be serviced by Agilent-trained technicians using the latest factory calibration procedures, automated repair diagnostics and genuine parts. You will always have the utmost confidence in your measurements. For information regarding self maintenance of this product, please contact your Agilent office.

Agilent offers a wide range of additional expert test and measurement services for your equipment, including initial start-up assistance, onsite education and training, as well as design, system integration, and project management.

For more information on repair and calibration services, go to:

www.agilent.com/find/removealldoubt

Product specifications and descriptions in this document subject to change without notice.

For more information on Agilent Technologies' products, applications or services, please contact your local Agilent office. The complete list is available at:

www.agilent.com/find/contactus

Americas

Canada	(877) 894-4414
Latin America	305 269 7500
United States	(800) 829-4444

Asia Pacific

Australia	1 800 629 485
China	800 810 0189
Hong Kong	800 938 693
India	1 800 112 929
Japan	0120 (421) 345
Korea	080 769 0800
Malaysia	1 800 888 848
Singapore	1 800 375 8100
Taiwan	0800 047 866
Thailand	1 800 226 008

Europe & Middle East

Austria	01 36027 71571
Belgium	32 (0) 2 404 93 40
Denmark	45 70 13 15 15
Finland	358 (0) 10 855 2100
France	0825 010 700*
	*0.125 €/minute
Germany	07031 464 6333
Ireland	1890 924 204
Israel	972-3-9288-504/544
Italy	39 02 92 60 8484
Netherlands	31 (0) 20 547 2111
Spain	34 (91) 631 3300
Sweden	0200-88 22 55
Switzerland	0800 80 53 53
United Kingdom	44 (0) 118 9276201

Other European Countries:

www.agilent.com/find/contactus

Revised: October 6, 2008

Related literature

Publication title	Publication type	Publication number
<i>Agilent Technologies 16900 Series logic analyzer</i>	Color brochure	5989-0420EN

© Agilent Technologies, Inc. 2008
Printed in USA, December 17, 2008
5989-6652EN

